

What is claimed is:

1. A component for a film forming equipment forming a thin film on a substrate, the component being characterized by that a metal film layer electrochemically less noble than the matrix metal material of said component is formed on the surface of the matrix metal material through thermal spraying, vapor depositing, sputtering, laminating or other process.
2. The component as claimed in claim 1, characterized by that a second metal film layer electrochemically more noble than said matrix metal material is formed on the surface of said metal film layer through thermal spraying, vapor depositing, sputtering, laminating or other process.
3. A method of cleaning a component for a film forming equipment, characterized by that after a thin film has been formed on the substrate by the film forming equipment, the component as claimed in claim 1 or 2 is dipped in a cleaning fluid to remove an deposited film consisting of the film forming material from the component.
4. The method as claimed in claim 3, characterized by that a positive electric field is applied to the matrix metal material of said component dipped in the cleaning fluid.